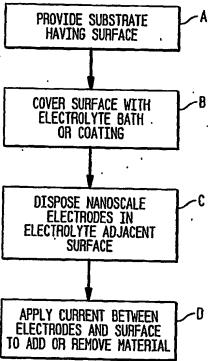
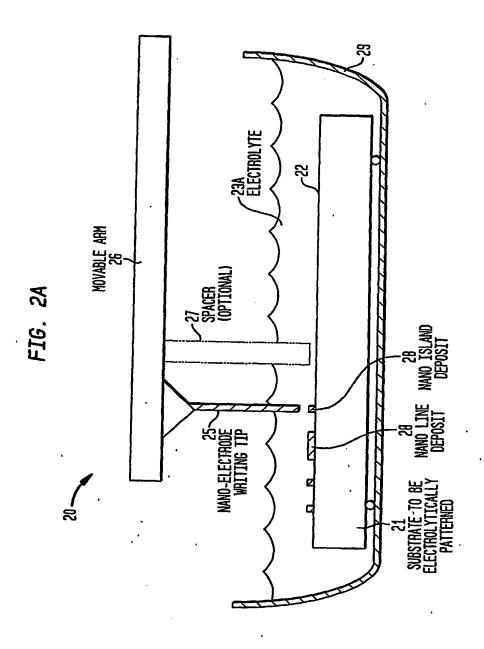
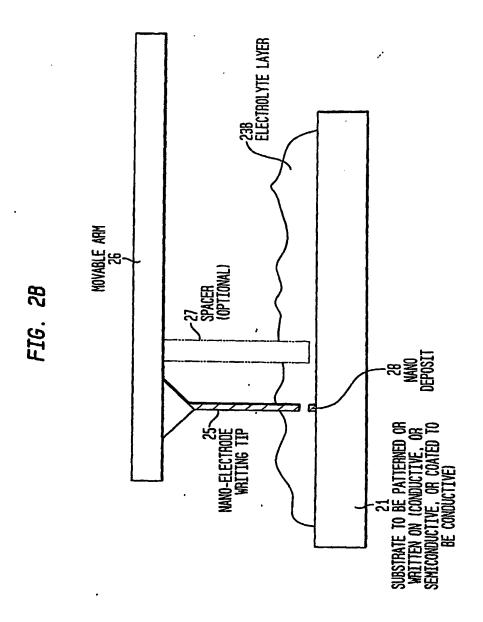
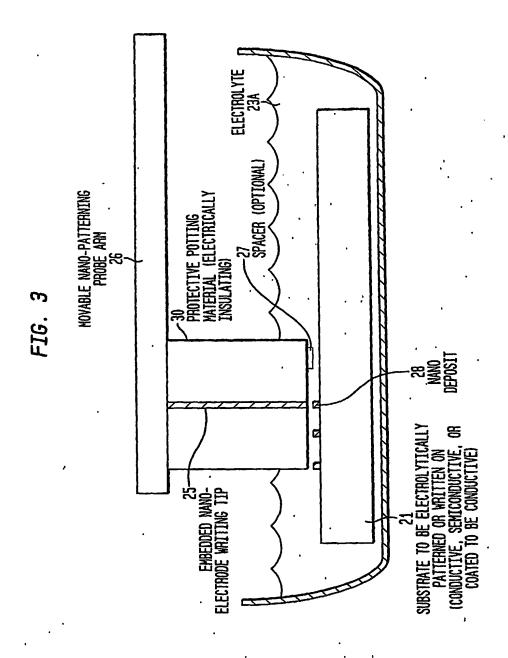
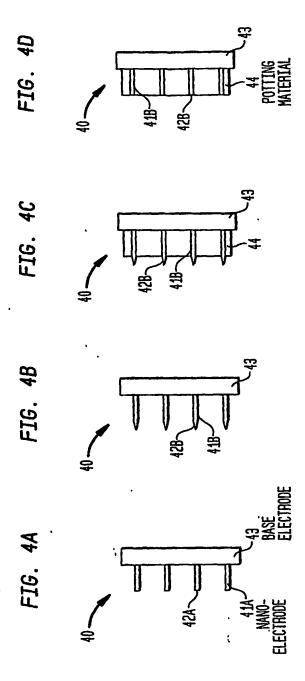
FIG. 1

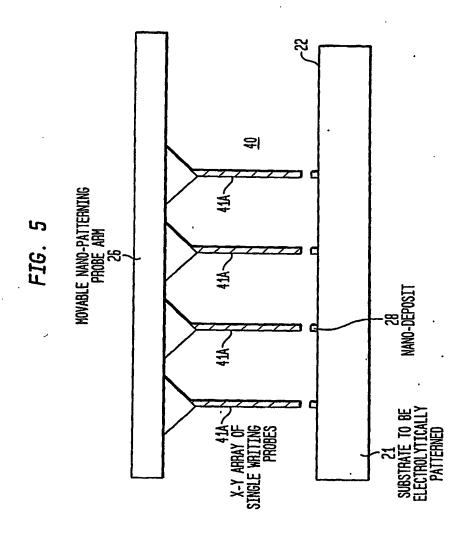


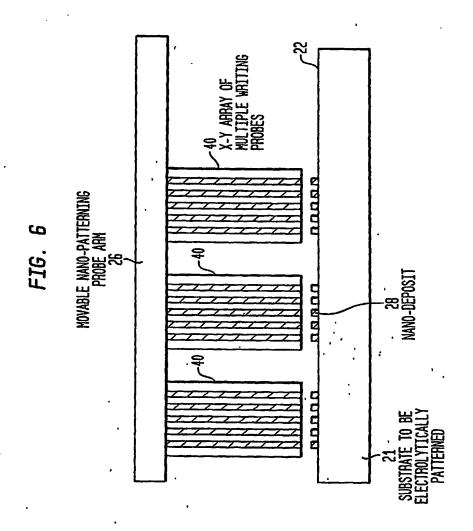




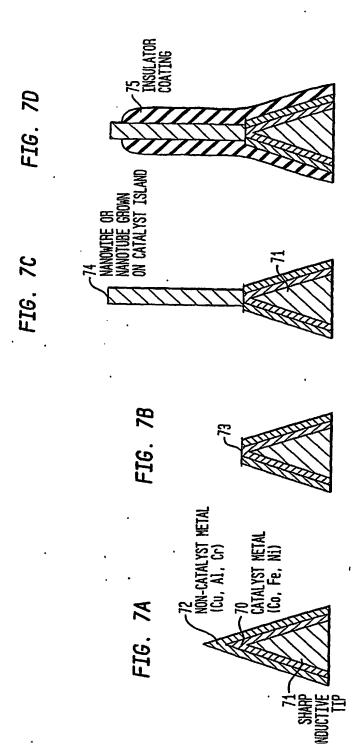


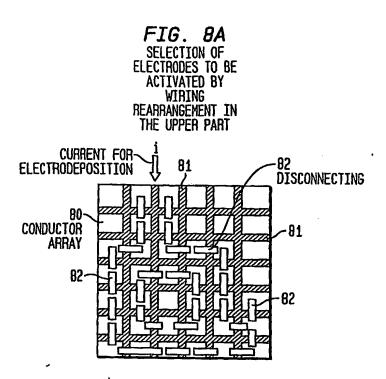


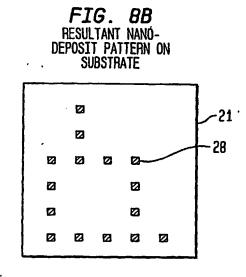


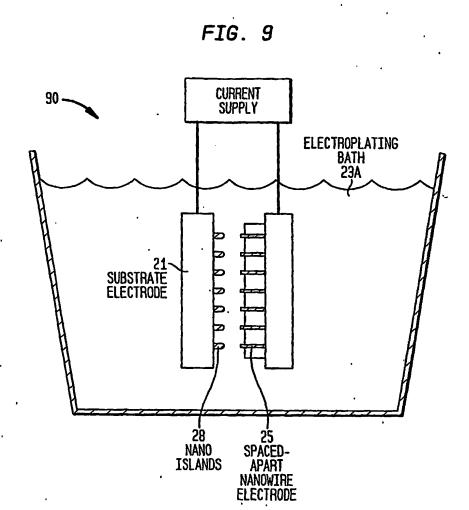


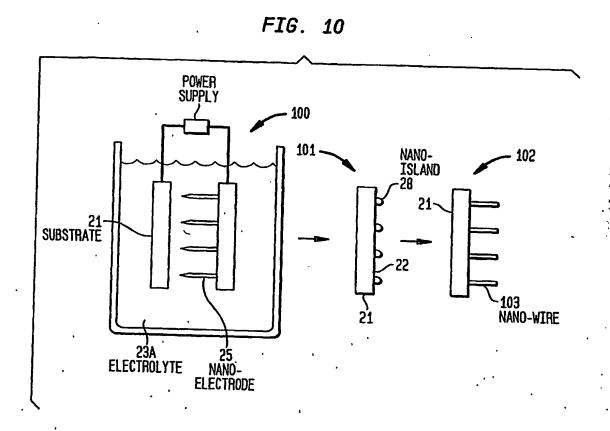


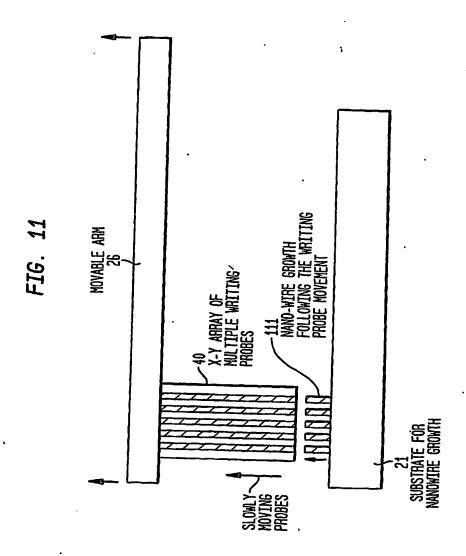


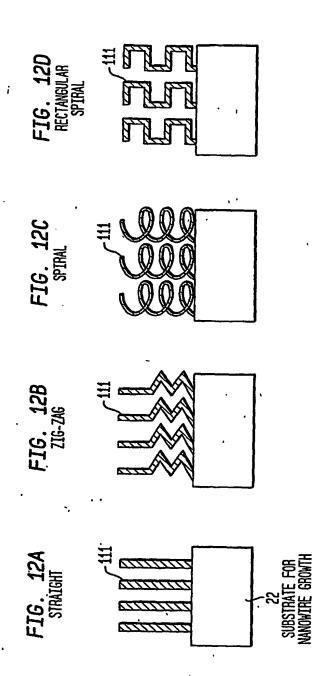






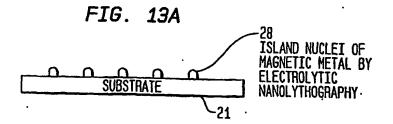


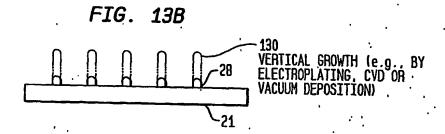


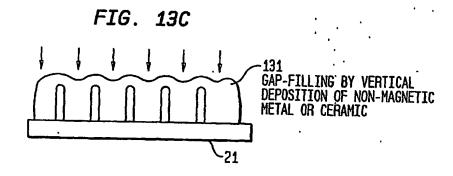


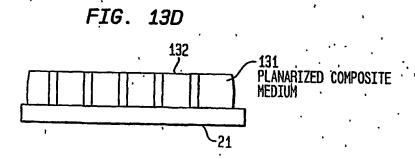
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FIG. 14A

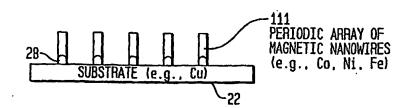


FIG. 14B OXIDIZE OR CVD TO FORM INSULATOR SKIN

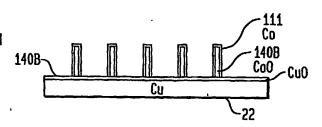


FIG. 14C H<sub>2</sub> REDUCTION

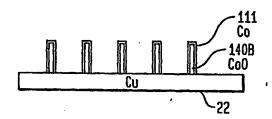


FIG. 14D
GAP-FILLING
ELECTRODEPOSITION

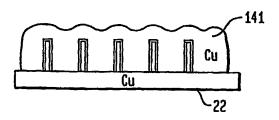


FIG. 14E
PLANARIZE
(e.g., BY CMP)

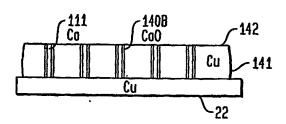


FIG. 15A

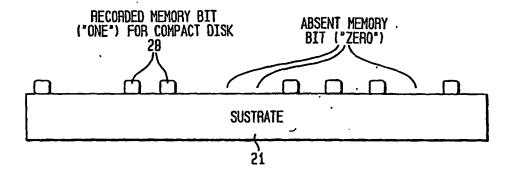
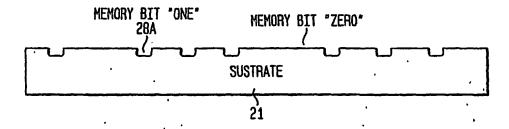


FIG. 15B



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FIG. 16A

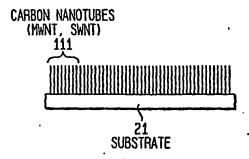


FIG. 16B



FIG. 16C

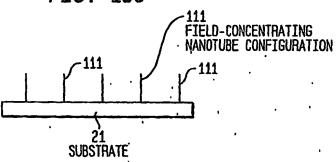


FIG. 16D

